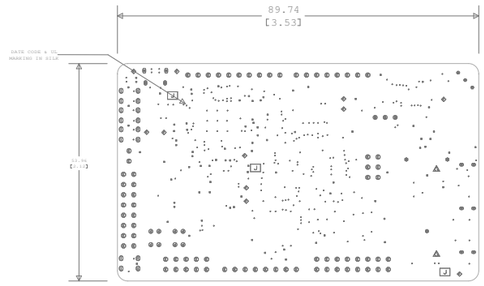
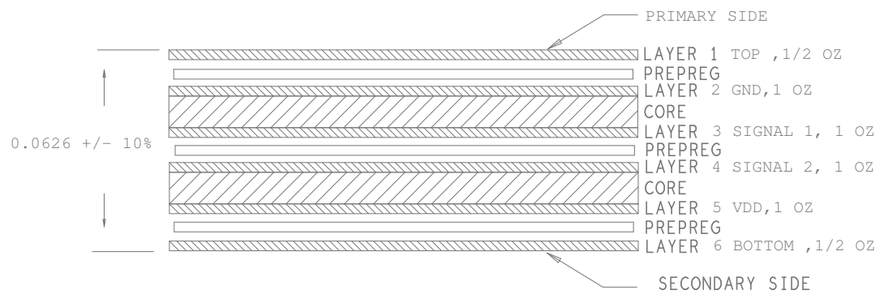
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
01	ALPHA RELEASE	05/20/16	AKAP
02	ALPHA RELEASE	06/22/16	AKAP



DRILL CHART: PSoC Pioneer kit				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
·	8.0	+3.0/-3.0	PLATED	262
·	10.0	+3.0/-3.0	PLATED	86
•	29.9	+3.0/-3.0	PLATED	3
◎	31.5	+3.0/-3.0	PLATED	8
◎	40.0	+3.0/-3.0	PLATED	76
•	42.9	+3.0/-3.0	PLATED	3
◇	43.0	+3.0/-3.0	PLATED	11
•	53.0	+3.0/-3.0	PLATED	3
△	72.8	+3.0/-3.0	PLATED	2
•	35.4	+2.0/-2.0	NON-PLATED	6
◎	46.0	+2.0/-2.0	NON-PLATED	16
◪	98.0	+2.0/-2.0	NON-PLATED	3
▪	41.3x25.6	+3.0/-3.0	PLATED	2
▪	47.2x27.6	+3.0/-3.0	PLATED	2



90E IMPEDANCE CONTROL ON 9MIL AND 16MIL SPACING USB CONNECTOR(REFDES J6)

NOTES:(UNLESS OTHERWISE SPECIFIED)

1. RoHS COMPLIANT CERTIFICATION OR MATERIAL DECLARATION REQUIRED.
2. MATERIAL:
   A. IS410 OR EQUIVALENT. MATERIAL MUST CONFORM TO UL94V-0.
   B. REFER TO AS MENTIONED IN CROSS SECTION AREA IN THIS DOCUMENT.
   C. OVERALL METAL TO METAL THICKNESS AS SPECIFIED IN THE CROSS SECTION DRAWING IN THE DOCUMENT.
3. DRILLING:
   A. DIAMETERS IN DRILL TABLE ARE FINISHED HOLE SIZES +/-.003 tol.
      UNLESS OTHERWISE SPECIFIED IN DRILL TABLE.
   B. TEARDROP ALLOWED ON ENTRY OF VIA ON EVERY TRACE LAYER.
4. PLATING:
      COPPER PLATING IN THRU-HOLES .001 min.
5. MARKING:
   A. SILKSCREEN IN WHITE NON-CONDUCTIVE EPOXY INK ON PRIMARY SIDE OF THE
      BOARD OR BOTH SIDES IF APPLICABLE.
   B. FABRICATOR TO PLACE DATE CODE, LOGO AND RoHS COMPILANT SYMBOL IN SILKSCREEN ON SECONDARY SIDE.
6. FINAL FABRICATION:
   A. SOLDRMASK PRIMARY AND SECONDARY SIDE OF BOARD USING LIQUID PHOTOIMAGABLE
      MASK MATERIAL OVER BARE COPPER. PER IPC-SM-840. MASK ARTWORKS PROVIDED
      ARE 1:1. SOLDERMASK COLOR **RED**
7. FINISH:
   A. SHALL BE IMMERSION GOLD(ENIG).
   B. NICKEL THICKNESS: 0.00010-0.00020in
   C. GOLD THICKNESS: 0.0000030-0.000010in
8. BOARDS SHALL BE PURCHASED FROM UL RECOGNIZED VENDORS ONLY.
   FLAMABILITY RATING (94-V0).
9. MANUFACTURE BOARD TO BE IN ACCORDANCE WITH PERFORMANCE STANDARD
   IPC-6011/6012 CLASS 2 BOARD TO BE INSPECTED PER IPC-600-A CLASS 2.
10. MAXIMUM WRAP OR TWIST SHALL NOT EXCEED .007 in/in.
11. TESTING:
   A. FABRICATOR TO ADD TEST STRUCTURES OR CUPONS AS NEEDED.
   B. T-LINE IMPEDENCE TO BE TESTED OR GUARANTEE WITHIN 10% IF SPECIFIED IN
      THE CROSS SECTION. TOLERANCE TO BE +/-10% UNLESS OTHERWISE SPECIFIED.

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN INCHES
TOLERANCES ON; ANGLES +/- 2°
2 PL DECIMALS +/- .010
3 PL DECIMALS +/- .005
THIRD ANGLE PROJECTIONS

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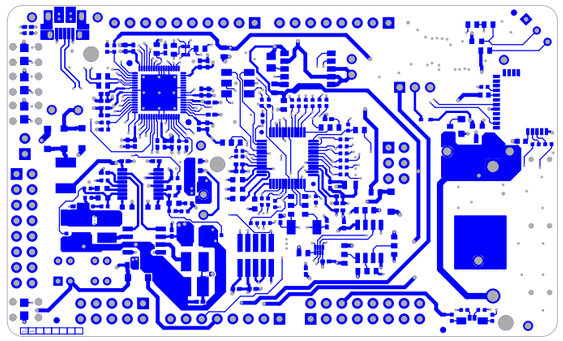
SIGNATURES		DATE
DRAWN	AKAP	06/22/16
CHECKED	AKAP	06/22/16
ENGRG	AKAP	06/22/16
ISSUED		

CYPRESS SEMICONDUCTOR
198 CHAMPION COURT
SAN JOSE, CA 95134
(408) 943-2600

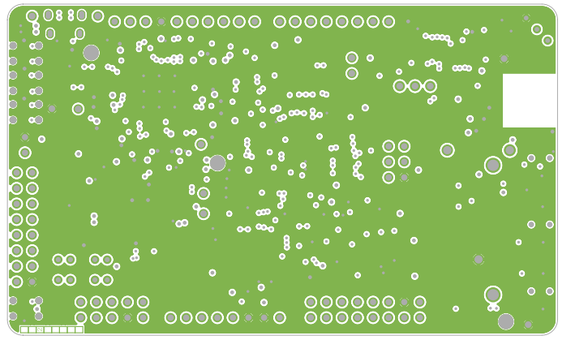
FABRICATION DRAWING
CY8CKIT-041-41XX
4100S PIONEER KIT

SIZE	FSCM NO	DWG NO	REV
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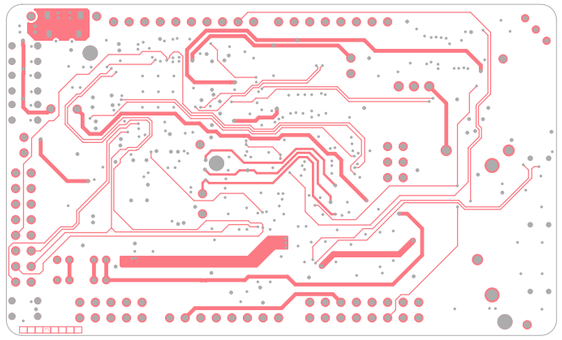
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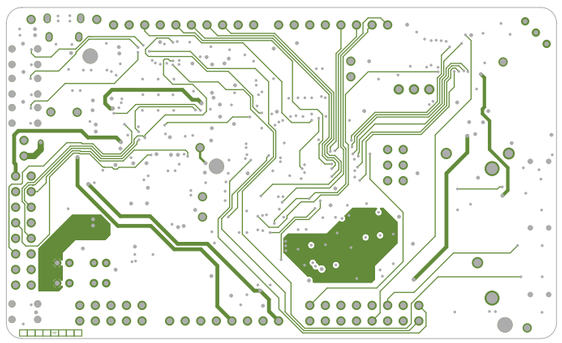
600-60345-01 REV02 PRIMARY SIDE



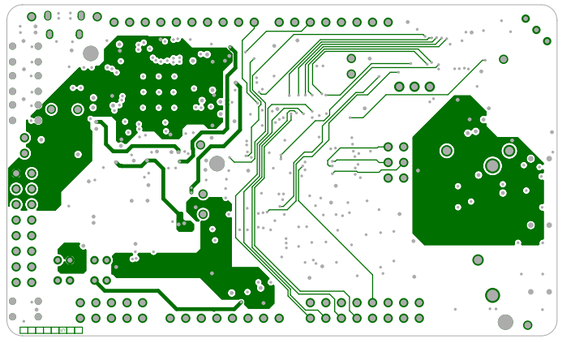
600-60345-01 REV02 GND LAYER



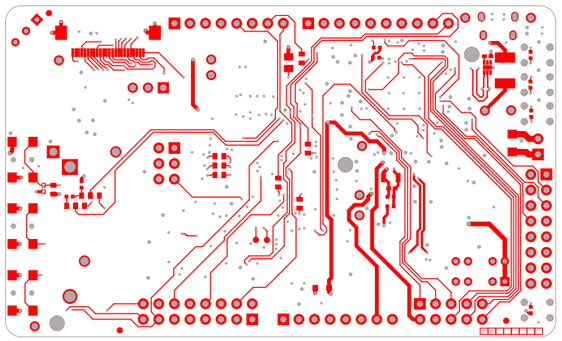
600-60345-01 REV02 SIGNAL1 LAYER



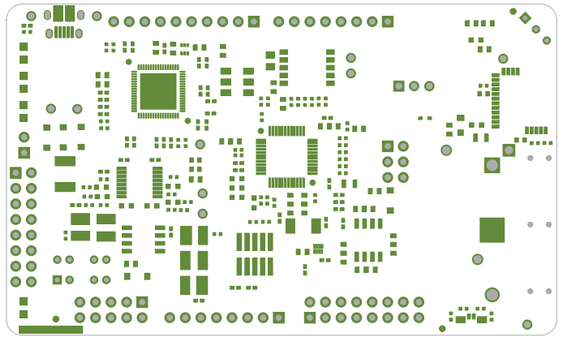
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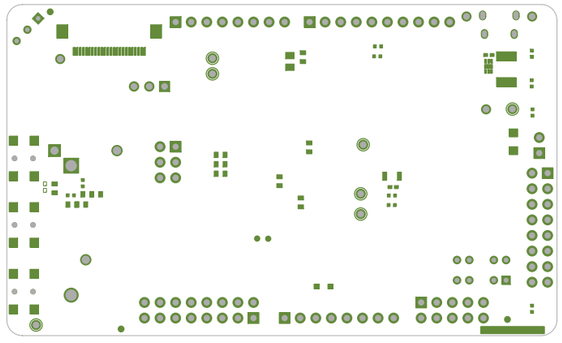
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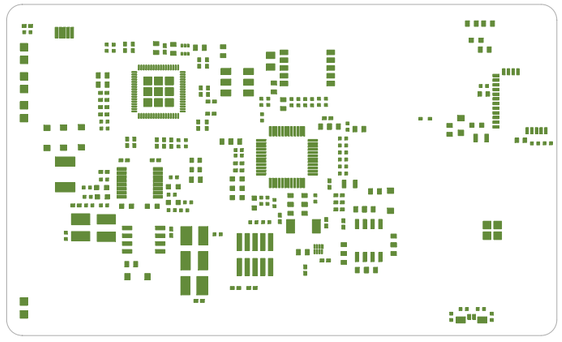
600-60345-01 REV02 SECONDARY SIDE



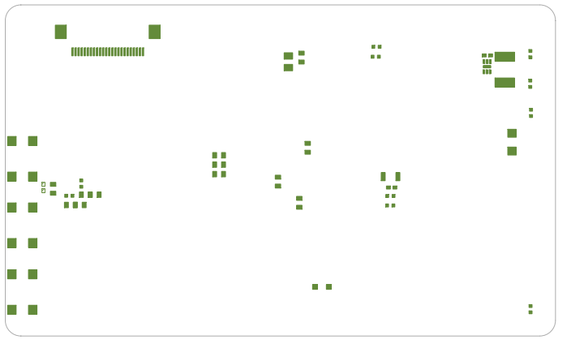
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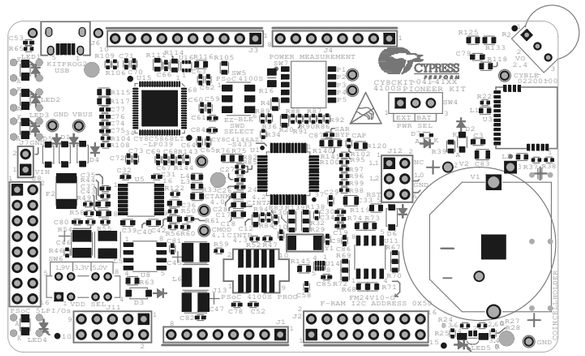
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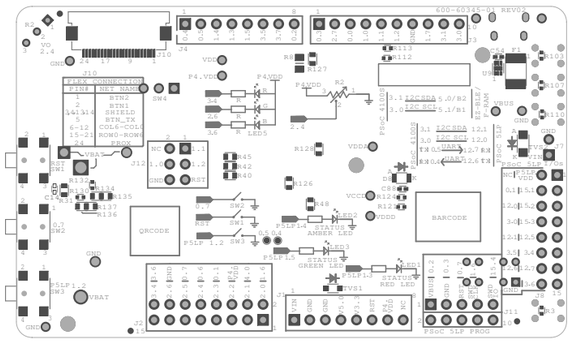
600-60345-01 REV02 PRIMARY SOLDERPASTE



600-60345-01 REV02 SECONDARY SOLDERPASTE



600-60345-01 REV02 PRIMARY SILKSCREEN



600-60345-01 REV02 SECONDARY SILKSCREEN